BOMcheck.net

Full Material Declaration for attached parts list

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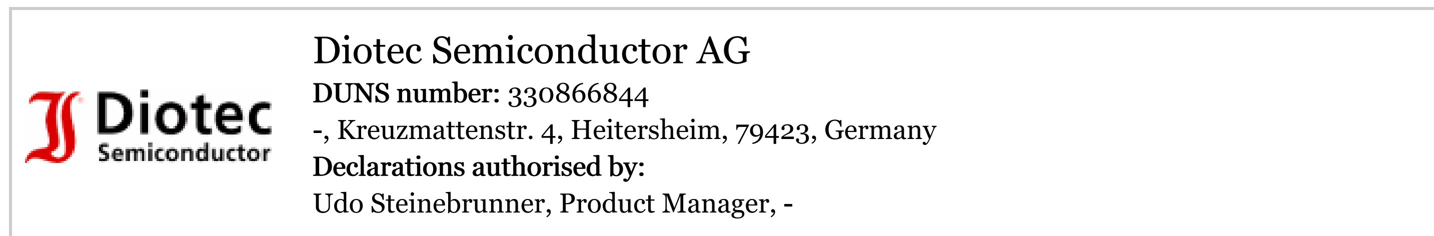

Diotec Semiconductor AG

DUNS number: 330866844
-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany
Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved on 27 October 2025, 11:32 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.2%	Nickel REACH Article 67 Exemption	7440-02-0	0.9%
			Gold	7440-57-5	10.3%
			Polydimethyl siloxane	63148-62-9	25.3%
			Silicon	7440-21-3	63.5%
Die attach	Lead and Lead alloys	0.1%	Silver	7440-22-4	1.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	93.5%
Encapsulation	EP (Epoxy resin)	23.3%	Carbon black	1333-86-4	1%
			Phenol, polymer with formaldehyde	9003-35-4	15%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	20%
			Quartz Exempt from other regulatory requirements	14808-60-7	64%
Leadfinish	Tin plating	2.4%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	74%	Copper	7440-50-8	100%

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Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-201 (DCN) HF	Diode axial	0.8	g

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